

Abstract of the Disclosure

**SEMICONDUCTOR PACKAGE CONTAINING AN INTEGRATED-CIRCUIT
CHIP SUPPORTED BY ELECTRICAL CONNECTION LEADS**

Semiconductor package containing an integrated-circuit chip, characterized in that it comprises a leadframe formed from spaced-apart electrical connection leads (5), the integrated-chip being fixed to or supported by a front surface of the leads, electrical connection means (16) for connecting the integrated-chip to the electrical connection leads and a block (20) of an encapsulation material in which at least the electrical connection leads are at least partly embedded.